Electronic Supplementary Material (ESI) for RSC Advances.

Electronic Supplementary Information

Relation between Temperature Memory Effect and Multiple-Shape Memory Behaviors Based on Polymer Networks

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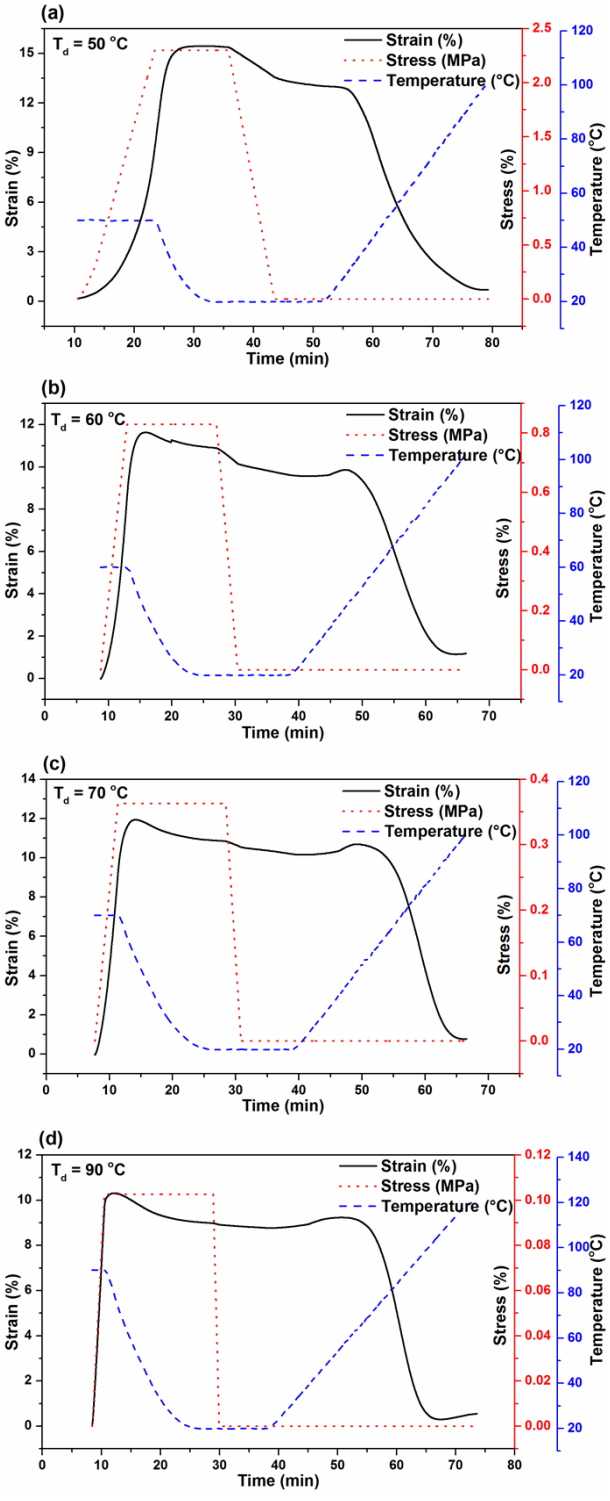


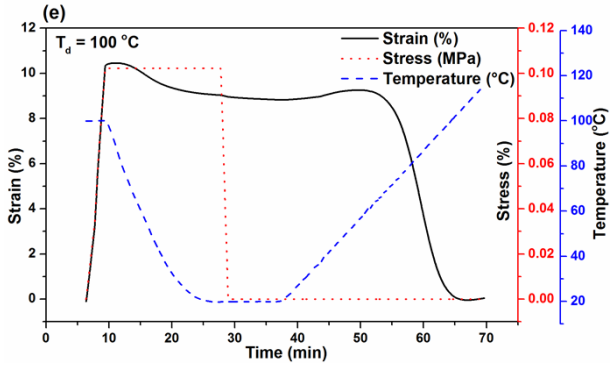
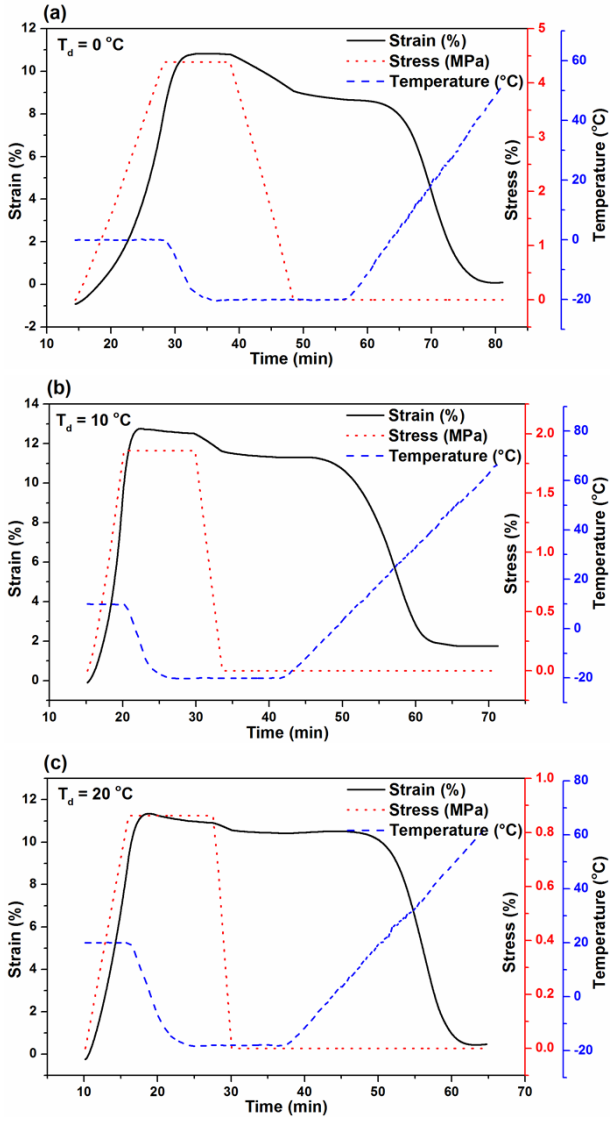


Figure S1. Dual-shape memory properties of PMMA/PEG semi-IPN at different T_d. (a) T_d = 50 °C, R_f = 85.1%, R_r = 95.4%. (b) T_d = 60 °C, R_f = 88.3%, R_r = 89.2%. (c) T_d = 70 °C, R_f = 93.9%, R_r = 93.0%. (d) T_d = 90 °C, R_f = 97.7%, R_r = 93.9%. (e) T_d = 100 °C, R_f = 97.7%, R_r = 99.5%.



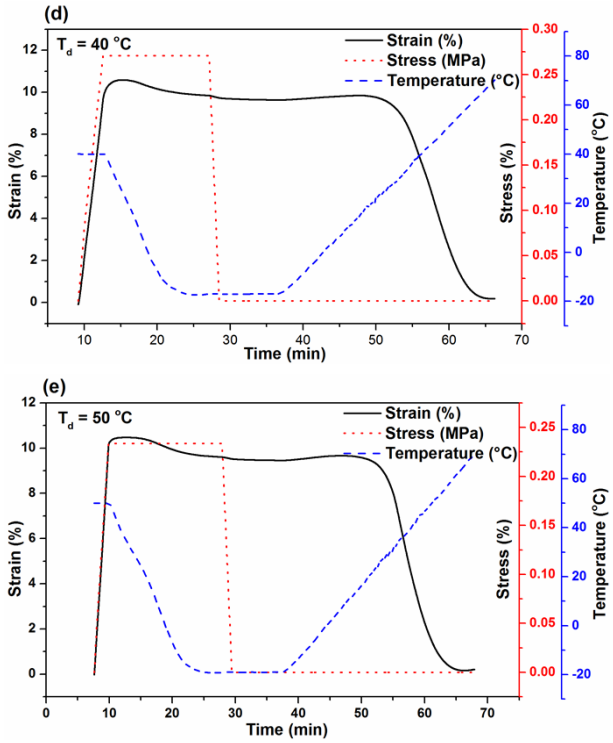


Figure S2. Dual-shape memory properties of PMMA-PCL CPN at different T_d. (a) T_d = 0 °C, R_f = 85.1%, R_r = 91.3%. (b) T_d = 10 °C, R_f = 90.5%, R_r = 85.4%. (c) T_d = 20 °C, R_f = 95.7%, R_r = 93.6%. (d) T_d = 40 °C, R_f = 97.9%, R_r = 98.1%. (e) T_d = 50 °C, R_f = 98.5%, R_r = 97.8%.